

Vishay Siliconix



# **Dual N-Channel 30 V (D-S) MOSFET**

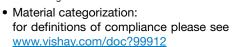


Marking code: MH

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	30					
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$	0.058					
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.073					
Q <sub>g</sub> typ. (nC)	1.8					
I <sub>D</sub> (A) <sup>a</sup>	3.7					
Configuration	Dual					

#### **FEATURES**

- TrenchFET® power MOSFET
- 100% R<sub>g</sub> tested

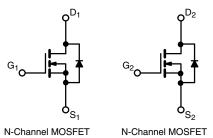




ROHS COMPLIANT HALOGEN FREE

### **APPLICATIONS**

- Load switch for portable applications
- DC/DC converters



ORDERING INFORMATION	
Package	TSOP-6
Lead (Pb)-free and halogen-free	Si3932DV-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	30	.,	
Gate-source voltage		V <sub>GS</sub>	± 20	V	
	T <sub>C</sub> = 25 °C		3.7		
Continuous durin surrent /T 150 °C)	T <sub>C</sub> = 70 °C	1 . 🗆	3		
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	3.4 b, c		
	T <sub>A</sub> = 70 °C		2.7 b, c	Α	
Pulsed drain current		I <sub>DM</sub>	15		
Continuous durin diada aument	T <sub>C</sub> = 25 °C	,	1.17		
Continuous source-drain diode current	T <sub>A</sub> = 25 °C	ls –	0.95 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		1.4		
Maximum power dissipation	T <sub>C</sub> = 70 °C	1 5 5	0.9	144	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.14 <sup>b, c</sup>	W	
	T <sub>A</sub> = 70 °C		0.73 <sup>b, c</sup>		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	.0	
Soldering recommendations (peak tempera		260	°C		

THERMAL RESISTANCE RATINGS							
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT			
Maximum junction-to-ambient b, d	t ≤ 5 s	$R_{thJA}$	93	110	°C/W		
Maximum junction-to-foot	Steady state	R <sub>thJF</sub>	75	90	C/W		

#### Notes

- a.  $T_C = 25 \, ^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 5 s
- d. Maximum under steady state conditions is 150 °C/W



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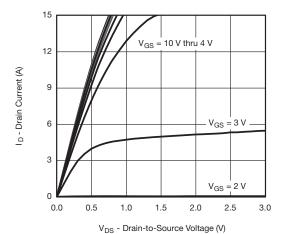
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				•		
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	1 050 A	-	29	-	mV/°C
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-4	-	
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2	-	2.2	V
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
7	I <sub>DSS</sub> -	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ
Zero gate voltage drain current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	-	-	10	
On-state drain current a	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10	-	-	Α
Duein accurate an atata mariatana 2		$V_{GS} = 10 \text{ V}, I_D = 3.4 \text{ A}$	-	0.047	0.058	_
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$	-	0.058	0.073	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3.4 A	-	10	-	S
Dynamic <sup>b</sup>	. '			•		
Input capacitance	C <sub>iss</sub>		-	235	-	
Output capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	45	-	pF
Reverse transfer capacitance	C <sub>rss</sub>		-	16	-	
Total gate charge	Q <sub>g</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.4 \text{ A}$	-	3.7	6	
			-	1.8	3	
Gate-source charge	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.4 \text{ A}$	-	0.74	-	nC
Gate-drain charge	Q <sub>gd</sub>		-	0.42	-	
Gate resistance	$R_g$	f = 1 MHz	1	5	10	Ω
Turn-on delay time	t <sub>d(on)</sub>		-	10	20	
Rise time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 5.6 $\Omega$	-	15	30	
Turn-off delay time	t <sub>d(off)</sub>	$I_D\cong 2.7$ A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$	-	10	20	
Fall time	t <sub>f</sub>		-	10	20	
Turn-on delay time	t <sub>d(on)</sub>		-	5	10	- ns - -
Rise time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_L = 5.6 \Omega$	-	15	30	
Turn-off delay time	t <sub>d(off)</sub>	$I_D\cong 2.7$ A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$	-	10	20	
Fall time	t <sub>f</sub>		-	10	20	
<b>Drain-Source Body Diode Characteristic</b>	es			•		
Continuous source-drain diode current	Is	T <sub>C</sub> = 25 °C	-	-	1.17	
Pulse diode forward current	I <sub>SM</sub>		-	-	15	Α
Body diode voltage	V <sub>SD</sub>	$I_S = 2.7 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.85	1.2	V
Body diode reverse recovery time	t <sub>rr</sub>		-	10	20	ns
Body diode reverse recovery charge	Q <sub>rr</sub>	$I_F = 2.7 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	4	10	nC
Reverse recovery fall time	ta	T <sub>J</sub> = 25 °C	-	6	-	
Reverse recovery rise time	t <sub>b</sub>		_	4	_	ns

#### Notes

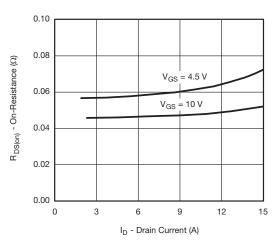
- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2%
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

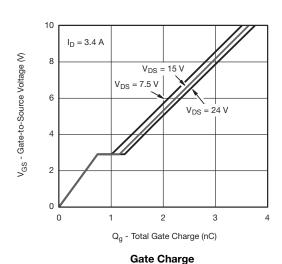


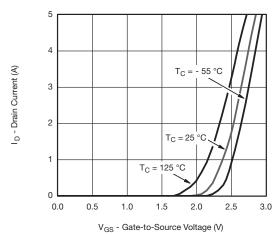


#### **Output Characteristics**

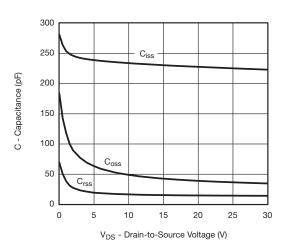


### On-Resistance vs. Drain Current and Gate Voltage

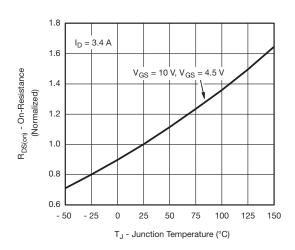




**Transfer Characteristics** 

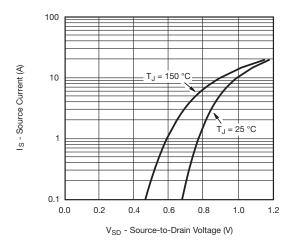


### Capacitance

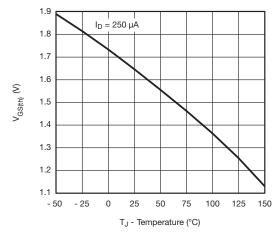


On-Resistance vs. Junction Temperature

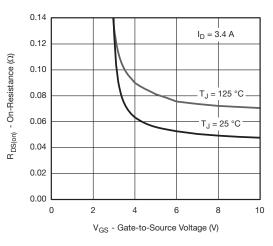




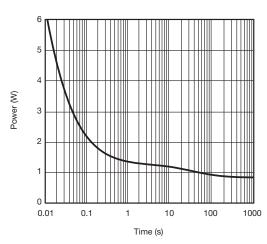
#### Source-Drain Diode Forward Voltage



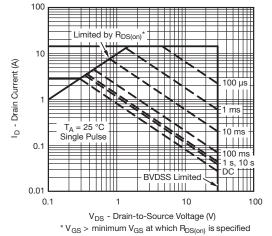
**Threshold Voltage** 



On-Resistance vs. Gate-to-Source Voltage

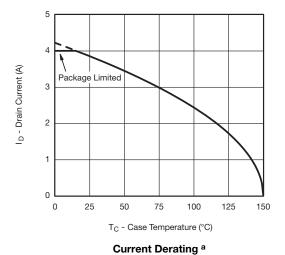


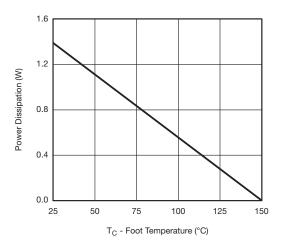
Single Pulse Power (Junction-to-Ambient)



Safe Operating Area, Junction-to-Ambient





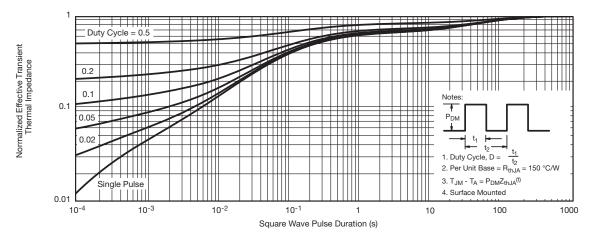


#### **Power Derating**

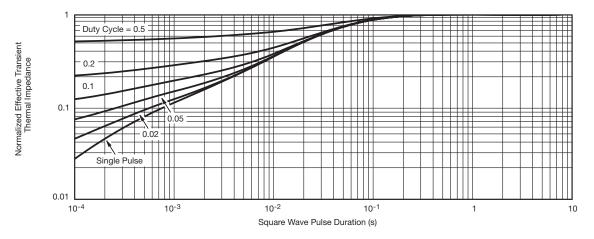
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

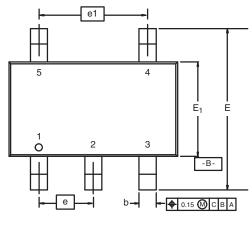
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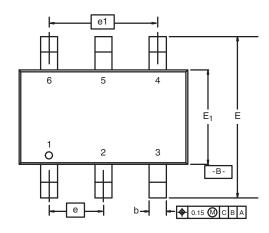




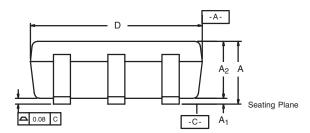
TSOP: 5/6-LEAD

**JEDEC Part Number: MO-193C** 

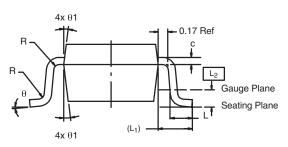




**5-LEAD TSOP** 







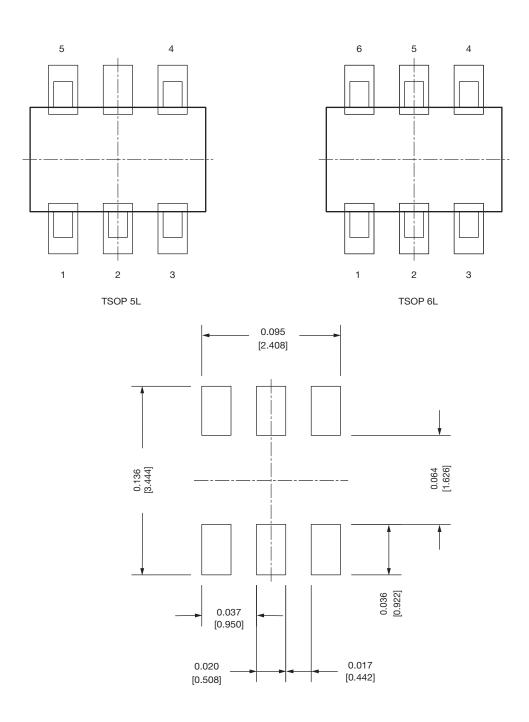
	MIL	LIMETER	RS	INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.91	-	1.10	0.036	-	0.043
A <sub>1</sub>	0.01	-	0.10	0.0004	-	0.004
A <sub>2</sub>	0.90	-	1.00	0.035	0.038	0.039
b	0.30	0.32	0.45	0.012	0.013	0.018
С	0.10	0.15	0.20	0.004	0.006	0.008
D	2.95	3.05	3.10	0.116	0.120	0.122
Е	2.70	2.85	2.98	0.106	0.112	0.117
E <sub>1</sub>	1.55	1.65	1.70	0.061	0.065	0.067
е		0.95 BSC		0.0374 BSC		
e <sub>1</sub>	1.80	1.90	2.00	0.071	0.075	0.079
L	0.32	-	0.50	0.012	-	0.020
L <sub>1</sub>		0.60 Ref	60 Ref 0.024 Ref			
L <sub>2</sub>	0.25 BSC			0.010 BSC		
R	0.10	-	-	0.004	-	-
θ	0°	4°	8°	0°	4°	8°
θ1	7° Nom			7° Nom		
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540						

DWG: 5540

Document Number: 71200 18-Dec-06



# Recommended Land Pattern For TSOP-5L / TSOP-6L



## Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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